

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claim 1 (currently amended): A substrate strip, which comprises:

(a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and

(b) at least one substrate supported on the supporting bars, the substrate being linked to the supporting bars by means of no more than two external tie bars, ~~wherein a semiconductor package formed on the substrate is free of the tie bars.~~

Claim 2 (original): The substrate strip of claim 1, wherein the substrate is dedicated for BGA application.

Claim 3 (original): The substrate strip of claim 1, wherein the substrate is linked to the frame by means of just two tie bars.

Claim 4 (original): The substrate strip of claim 3, wherein the two tie bars are arranged on two adjacent corners of the substrate.

Claim 5 (original): The substrate strip of claim 3, wherein the two tie bars are arranged on diagonally opposite corners of the substrate.

Claim 6 (original): The substrate strip of claim 3, wherein one of the two tie bars is arranged on one corner of the substrate and the other is arranged on one side of the substrate.

Claim 7 (original): The substrate strip of claim 1, wherein the substrate is linked to the frame by means of just one tie bar.

Claim 8 (original): The substrate strip of claim 7, wherein the just one tie bar is arranged on the substrate's gating corner.

Claim 9 (currently amended): A substrate strip, which comprises:

(a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and

(b) at least one substrate supported on the supporting bars, the substrate being linked to the supporting bars by means of a-an external two-point linkage structure consisting of just two tie bars linked to the supporting bars, ~~wherein a semiconductor package formed on the substrate is free of the tie bars.~~

Claim 10 (original): The substrate strip of claim 9, wherein the substrate is dedicated for BGA application.

Claim 11 (original): The substrate strip of claim 9, wherein the two tie bars are arranged on two adjacent corners of the substrate.

Claim 12 (original): The substrate strip of claim 9, wherein the two tie bars are arranged on diagonally opposite corners of the substrate.

Claim 13 (original): The substrate strip of claim 9, wherein one of the two tie bars is arranged on one corner of the substrate and the other is arranged on one side of the substrate.

Claim 14 (currently amended): A substrate strip, which comprises:

(a) a frame having a pair of parallel supporting bars including a first supporting bar and a second supporting bar; and

(b) at least one substrate supported on the supporting bars, the substrate being linked to the supporting bars by means of a-an external one-point linkage structure consisting of just one tie bar linked to one of the two supporting bars, ~~wherein a semiconductor package formed on the substrate is free of the tie bar.~~

Claim 15 (original): The substrate strip of claim 14, wherein the substrate is dedicated for BGA application.

Claim 16 (original): The substrate strip of claim 14, wherein the just one tie bar is arranged on the substrate's gating corner.